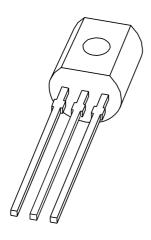
### **DISCRETE SEMICONDUCTORS**

# DATA SHEET



### BSN254; BSN254A N-channel enhancement mode vertical D-MOS transistor

Product specification Supersedes data of 1997 Jun 23 2002 Feb 19





### N-channel enhancement mode vertical D-MOS transistor

**BSN254**; **BSN254A** 

#### **FEATURES**

- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown
- Low R<sub>DSon</sub>.

### **APPLICATIONS**

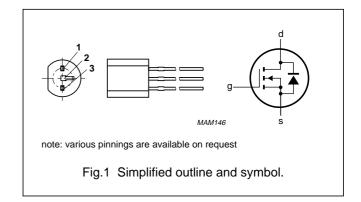
- Line current interruptor in telephone sets
- Relay, high-speed and line transformer drivers.

### **DESCRIPTION**

N-channel enhancement mode vertical D-MOS transistor in a SOT54 (TO-92) variant package.

#### **PINNING - SOT54 variant**

PIN	DESCRIPTION				
PIN	BSN254	BSN254A			
1	gate	source			
2	drain	gate			
3	source	drain			



### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
V <sub>DS</sub>	drain-source voltage (DC)		_	250	٧
I <sub>D</sub>	drain current (DC)		_	310	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	_	1	W
R <sub>DSon</sub>	drain-source on-state resistance	$I_D = 300 \text{ mA}; V_{GS} = 10 \text{ V}$	2.8	5	Ω
$V_{GSth}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$	_	2	٧

### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	PARAMETER CONDITIONS		MAX.	UNIT
V <sub>DS</sub>	drain-source voltage (DC)		_	250	V
V <sub>GSO</sub>	gate-source voltage (DC)	open drain	_	±20	V
I <sub>D</sub>	drain current (DC)		_	310	mA
I <sub>DM</sub>	peak drain current		_	1.25	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	1	W
T <sub>stg</sub>	storage temperature		-55	+150	°C
T <sub>i</sub>	junction temperature		_	150	°C

### Note

1. Device mounted on a printed-circuit board; maximum lead length 4 mm; mounting pad for drain lead minimum  $10 \times 10$  mm.

# N-channel enhancement mode vertical D-MOS transistor

BSN254; BSN254A

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient; note 1	125	K/W

### Note

1. Device mounted on a printed-circuit board; maximum lead length 4 mm; mounting pad for drain lead minimum  $10 \times 10$  mm.

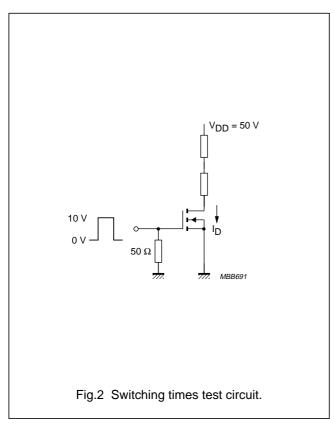
### **CHARACTERISTICS**

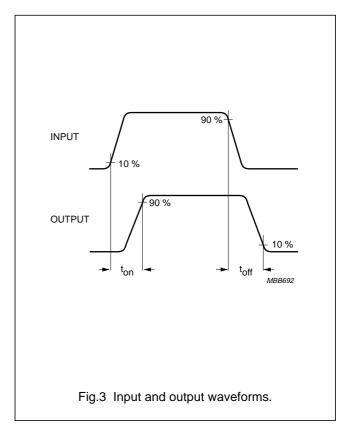
 $T_i = 25$  °C unless otherwise specified.

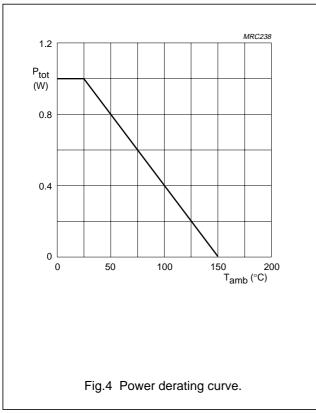
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$I_D = 10 \mu A; V_{GS} = 0$	250	_	_	V
I <sub>GSS</sub>	gate-source leakage current	$V_{GS} = \pm 20 \text{ V}; V_{DS} = 0$	_	_	±100	nA
$V_{GSth}$	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$	0.8	_	2	٧
R <sub>DSon</sub>	drain-source on-state resistance	$I_D = 20 \text{ mA}; V_{GS} = 2.4 \text{ V}$	_	_	7.5	Ω
		I <sub>D</sub> = 300 mA; V <sub>GS</sub> = 10 V	_	2.8	5	Ω
I <sub>DSS</sub>	drain-source leakage current $V_{DS} = 200 \text{ V}; V_{GS} = 0$		_	_	1	μΑ
Y <sub>fs</sub>	transfer admittance	$I_D = 300 \text{ mA}; V_{DS} = 25 \text{ V}$	200	600	_	mS
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0; f = 1 MHz	_	100	120	pF
C <sub>oss</sub>	output capacitance	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0; f = 1 MHz	_	21	30	pF
C <sub>rss</sub>	feedback capacitance	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0; f = 1 MHz	_	10	15	pF
Switching tir	nes (see Figs 2 and 3)			•		
t <sub>on</sub>	turn-on time	$I_D$ = 250 mA; $V_{DD}$ = 50 V; $V_{GS}$ = 0 to 10 V	_	6	10	ns
t <sub>off</sub>	turn-off time	$I_D$ = 250 mA; $V_{DD}$ = 50 V; $V_{GS}$ = 10 to 0 V	_	47	60	ns

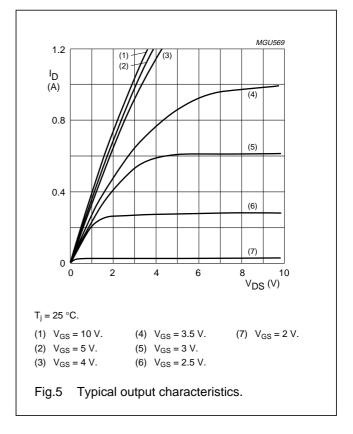
## N-channel enhancement mode vertical D-MOS transistor

### BSN254; BSN254A



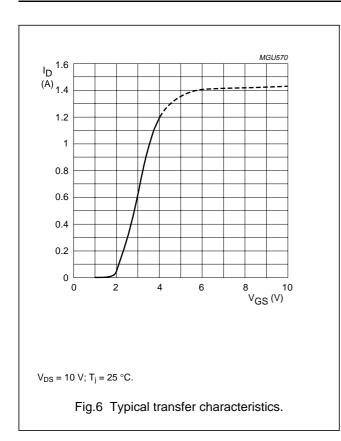






### N-channel enhancement mode vertical D-MOS transistor

BSN254; BSN254A



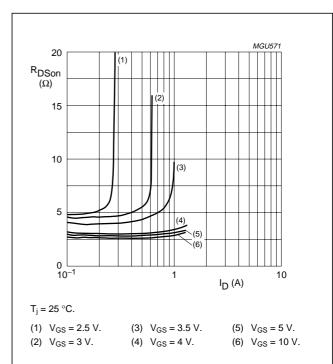


Fig.7 Drain-source on-state resistance as a function of drain current; typical values.

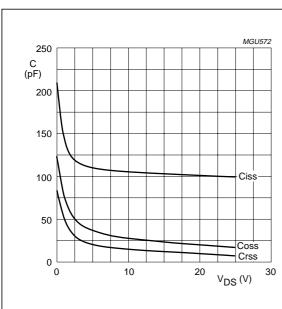


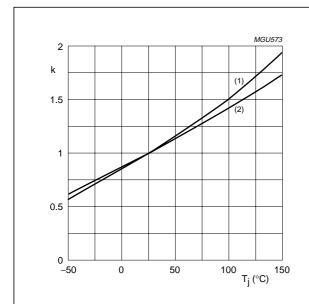
Fig.8 Input, output and feedback capacitance as functions of drain-source voltage; typical values.

5

 $V_{GS}$  = 0; f = 1 MHz;  $T_j$  = 25 °C.

## N-channel enhancement mode vertical D-MOS transistor

BSN254; BSN254A

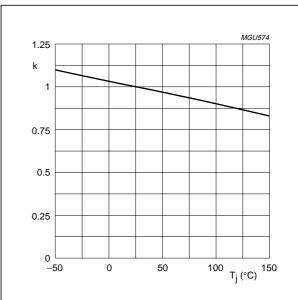


$$k = \frac{R_{DSon} \text{ at } T_j}{R_{DSon} \text{ at } 25 \text{ }^{\circ}\text{C}}$$

Typical R<sub>DSon:</sub>

- (1)  $I_D = 250 \text{ mA}$ ;  $V_{GS} = 10 \text{ V}$ .
- (2)  $I_D = 20 \text{ mA}$ ;  $V_{GS} = 2.4 \text{ V}$ .

Fig.9 Temperature coefficient of drain-source on-state resistance; typical values.



$$k = \frac{V_{GSth} \text{ at } T_j}{V_{GSth} \text{ at } 25 \text{ }^{\circ}\text{C}}$$

Typical V<sub>GSth</sub> at 1 mA.

Fig.10 Temperature coefficient of gate-source threshold voltage; typical values.

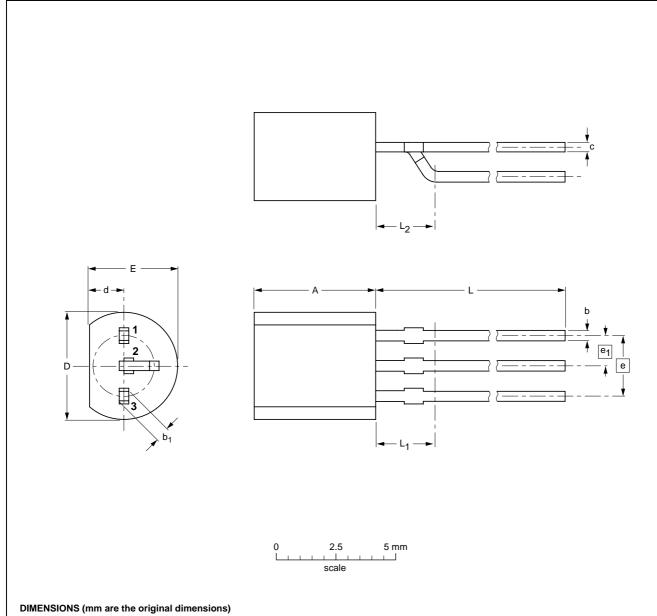
## N-channel enhancement mode vertical D-MOS transistor

BSN254; BSN254A

### **PACKAGE OUTLINE**

Plastic single-ended leaded (through hole) package; 3 leads (on-circle)

SOT54 variant



UNIT	Α	b	b <sub>1</sub>	С	D	d	E	е	e <sub>1</sub>	L	L <sub>1</sub> <sup>(1)</sup> max	L <sub>2</sub> max
mm	5.2 5.0	0.48 0.40	0.66 0.56	0.45 0.40	4.8 4.4	1.7 1.4	4.2 3.6	2.54	1.27	14.5 12.7	2.5	2.5

#### Notes

1. Terminal dimensions within this zone are uncontrolled to allow for flow of plastic and terminal irregularities.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT54 variant		TO-92 variant	SC-43			98-03-26

### N-channel enhancement mode vertical D-MOS transistor

BSN254; BSN254A

#### **DATA SHEET STATUS**

DATA SHEET STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
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BSN254; BSN254A

**NOTES** 

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BSN254; BSN254A

**NOTES** 

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BSN254; BSN254A

**NOTES** 

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#### **Contact information**

For additional information please visit http://www.semiconductors.philips.com. Fax: +31 40 27 24825 For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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